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Call for Papers

2nd INFORMS Conference on Financial Engineering and Fintech

Paper Submission Portal - Submit your paper via Microsoft CMT

Important Dates

- **Paper Submission Deadline:** July 10, 2026
- **Conference Dates:** November 6–7, 2026

We are pleased to announce the 2nd INFORMS Conference on Financial Engineering and Fintech, dedicated to advancing research and innovation at the intersection of finance, engineering, and technology. This conference provides a premier platform for academics, practitioners, and industry experts to share cutting-edge research, exchange ideas, and foster collaborations in the rapidly evolving fields of financial engineering and fintech.

Conference Themes

We invite original research papers on, but not limited to, the following topics:

- Quantitative finance and risk management
- Algorithmic and high-frequency trading
- Blockchain technology and cryptocurrencies
- Machine learning and artificial intelligence in finance
- Financial data analytics and big data applications
- Fintech innovations and digital banking
- Portfolio optimization and asset management
- Regulatory technology (RegTech) and compliance
- Financial modeling and simulation
- Credit risk and default prediction
- Behavioral finance and market microstructure

Submission Guidelines:

- Please submit your extended abstract via the online submission system by the deadline.

Important Dates:

- Paper Submission Deadline: July 10, 2026
- Notification of Acceptance: July 30, 2026
- Conference Dates: November 6&7, 2026

Who Should Attend:
This conference welcomes researchers, practitioners, policymakers, and students interested in financial engineering, fintech, and related disciplines.

Best Paper Awards:
We are happy to announce the following awards, sponsored NSF CRAFT & RCQF-HKPU:
BEST CONFERENCE PAPER - $2.000 –
BEST STUDENT PAPER AWARD - $1.000 –

Scientific Committee Members:
Min Dai (Committee Chair), Hong Kong Polytechnic University
Steven Yang (Local Organizer), Stevens Institute of Technology
Agostino Capponi, Columbia University
Zach Feinstein, Stevens Institute of Technology
Kay Giesecke, Stanford University
Martin Haugh, Imperial College
Xuedong He, Chinese University of Hong Kong
Steven Kou, Boston University
Renyuan Xu, Stanford University

Conference Venue:
University Center Complex - TechFlex Conference Center
Stevens Institute of Technology
1 Castle Point Terrace
Hoboken, NJ 07030
For more information, submission guidelines, and registration details, please visit:
https://www.stevens.edu/page-right-nav/2026-informs-conference-on-financial-engineering-and-fintech